

# EUROPEAN PATENT OFFICE

## Patent Abstracts of Japan

PUBLICATION NUMBER : 10215047  
PUBLICATION DATE : 11-08-98

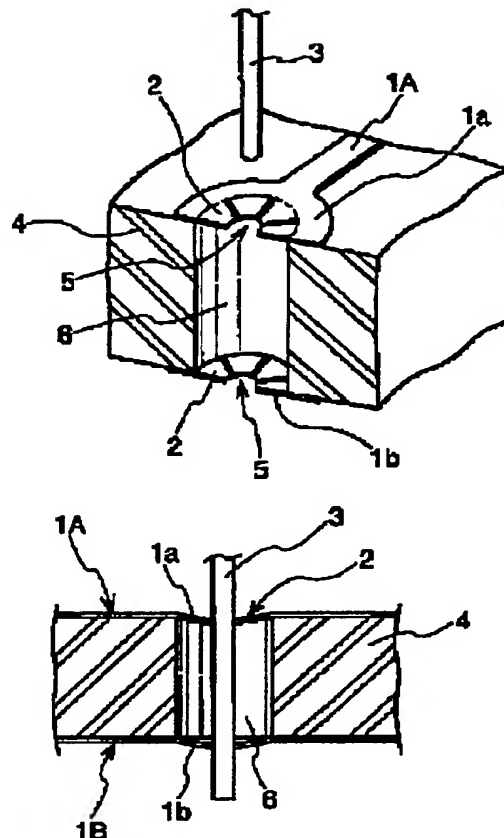
APPLICATION DATE : 30-01-97  
APPLICATION NUMBER : 09017101

APPLICANT : NEC ENG LTD;

INVENTOR : KURUMISAWA YUUJI;

INT.CL. : H05K 1/11 H01R 9/09 H05K 3/34

TITLE : PRINTED BOARD



**ABSTRACT :** **PROBLEM TO BE SOLVED:** To provide a printed board wherein interconnections between circuit wirings formed on both surfaces of the printed board can be securely maintained regardless of the temperature change, etc.

**SOLUTION:** A printed board is provided with an insulating substrate 4 with a through hole 6, a circuit wiring 1A formed on one surface of the substrate 4, a circuit wiring 1B formed on the other surface of the substrate 4, and a lead 3 for connecting a connecting portion 1a connected to the circuit wiring 1A to a connecting portion 1b connected to the circuit wiring 1B. The connecting portion 1a is provided with a plurality of tongues 2 covering at least a portion of the other open end of the through hole 6. The lead 3 is inserted into the through hole 6, and is held by the ends of a plurality of tongues 2 formed at the connecting portion 1a and the ends of a plurality of tongues 2 formed at the connecting portion 1b.

COPYRIGHT: (C)1998,JPO